

IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A semiconductor integrated circuit device comprising a semiconductor substrate and a semiconductor chip having bumps, which are used electrically connecting by face down bonding and provided in with a terminal section on a surface of a the semiconductor substrate thereof, said semiconductor integrated circuit device further comprising:

facedown-bonding dummy bumps which are connected non-electrically and disposed in a vicinity of one or more corner section of four corners of a semiconductor chip, wherein said bumps are arranged along and spaced from a peripheral edge of the semiconductor integrated circuit device and an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps, the height of the facedown dummy bonding bumps being the same as the height of the facedown bonding bumps.

2. (Currently amended) The semiconductor integrated circuit device according to claim 1, wherein said dummy bumps are functioning act as shock absorbing members for alleviating load stress due to the facedown bonding, and are overlapped with a wiring are not electrically connected to a wiring of which part is disposed to be overlapped to said facedown bonding dummy bumps with at least one insulating film being interposed in-between.